



SP-325

Transparent Silicone Gel

Features

- Transparent liquid silicone rubber, low viscosity, easy to mix & apply
- Low exothermic reaction & low shrinkage when curing. Ideal for encapsulating temperature sensitive and stress sensitive parts or modules.
- Transparent after cured, good resistance to environmental aging & moisture, great flexibility to buffer mechanical vibration and shock
- Excellent repair ability, cured elastomer can be removed by scraping or cutting; after repaired, potting & curing can be done to the repair area with care. If the area is polluted, clean it or use a primer before potting.

Applications

- Designed for potting or coating electrical / electronic components that demand insulation, moisture proof and weathering resistant, eg. indoor / outdoor LED modules, electronic boards of bathroom accessories, etc.
- Designed for components that will need a repairable material, eg. fuse holder, modules, etc.
- Designed for potting circuit boards to fix parts in place and offer shock proof and thick coating

Specifications

Color	:	Transparent
Viscosity of Mixture	:	@25°C 1100 ~ 1600 cps
Mix Ratio	:	By weight 100 : 100
Gel Time	:	@25°C 1-2 hours
Cure Time	:	@25°C 24 hours
Operational Temperature	:	-45°C ~ 200°C
Dielectric Strength	:	18 kV/mm
Hardness	:	Shore A 12~18
Volume Resistivity	:	1.0 x 10 ¹³ ohm-cm
Dielectric Constant	:	@1MHz 3.3
Dissipation Factor	:	@1MHz 0.001
Shelf Life	:	@25°C 6 months (unopened)

傑地有限公司

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Notes

1. All component / module surfaces to be potted and tools used must be clean and dry. Degrease and wash off any contaminants that could impair the result or transparency.
2. If problems of foaming or bubbling on potted components are noticed, try not to pot in thick sections or try multiple pouring. Or, vacuum the mixture before pouring or vacuum the potted components after potting to ensure bubble-free surfaces.
3. Some organic compounds that contain sulfur, phosphorous and nitrogen may inhibit or interfere with the curing reaction to cause hard-to-cure problems. If there are contaminants on parts like demould agents, sulfurous materials, flux remaining or organic metal compounds, please try with small amount first or wash them off, clean and dry all surfaces before applying.
4. Please use up the material asap after opened; or, keep this product tightly sealed to avoid water contamination.